

# E1SDA25-26.5625M TR



## ITEM DESCRIPTION

Quartz Crystal Resonator HC49/UP Short 2 Pad Surface Mount (SMD) 3.2mm Height Metal Resistance Weld Seal 26.5625MHz  $\pm 30$ ppm at 25°C,  $\pm 50$ ppm over 0°C to +70°C 25pF Parallel Resonant

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	26.5625MHz
Frequency Tolerance/Stability	$\pm 30$ ppm at 25°C, $\pm 50$ ppm over 0°C to +70°C
Aging at 25°C	$\pm 5$ ppm/year Maximum
Load Capacitance	25pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

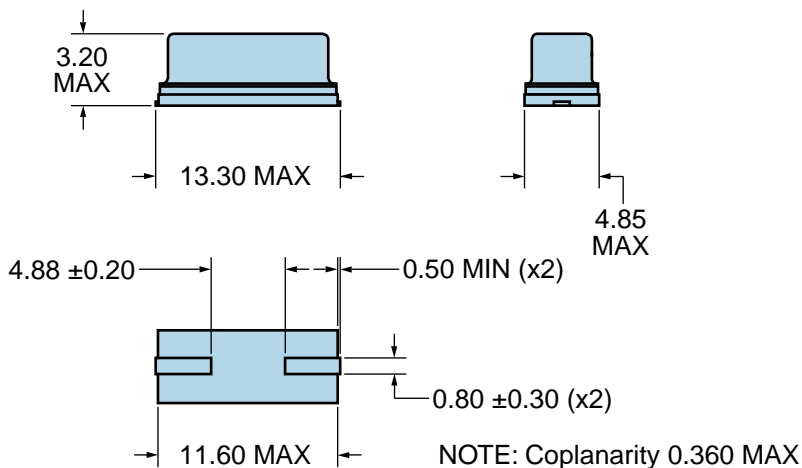
## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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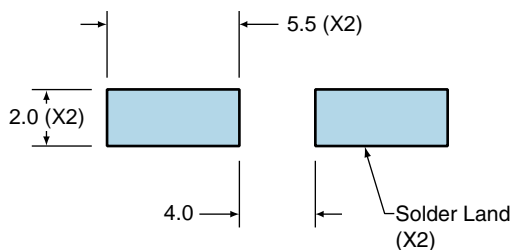
## MECHANICAL DIMENSIONS (all dimensions in millimeters)

LINE	MARKING
1	<b>E26.562M</b> E=Ecliptek Designator



## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

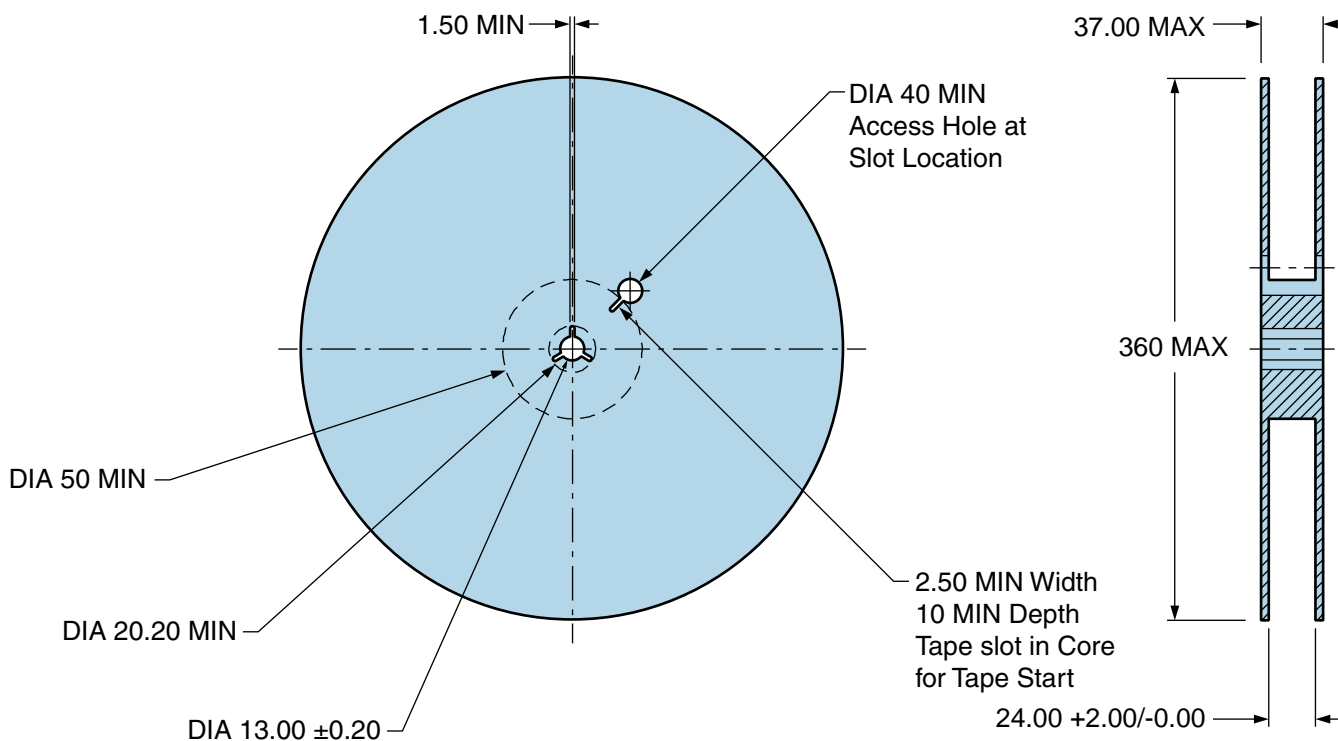
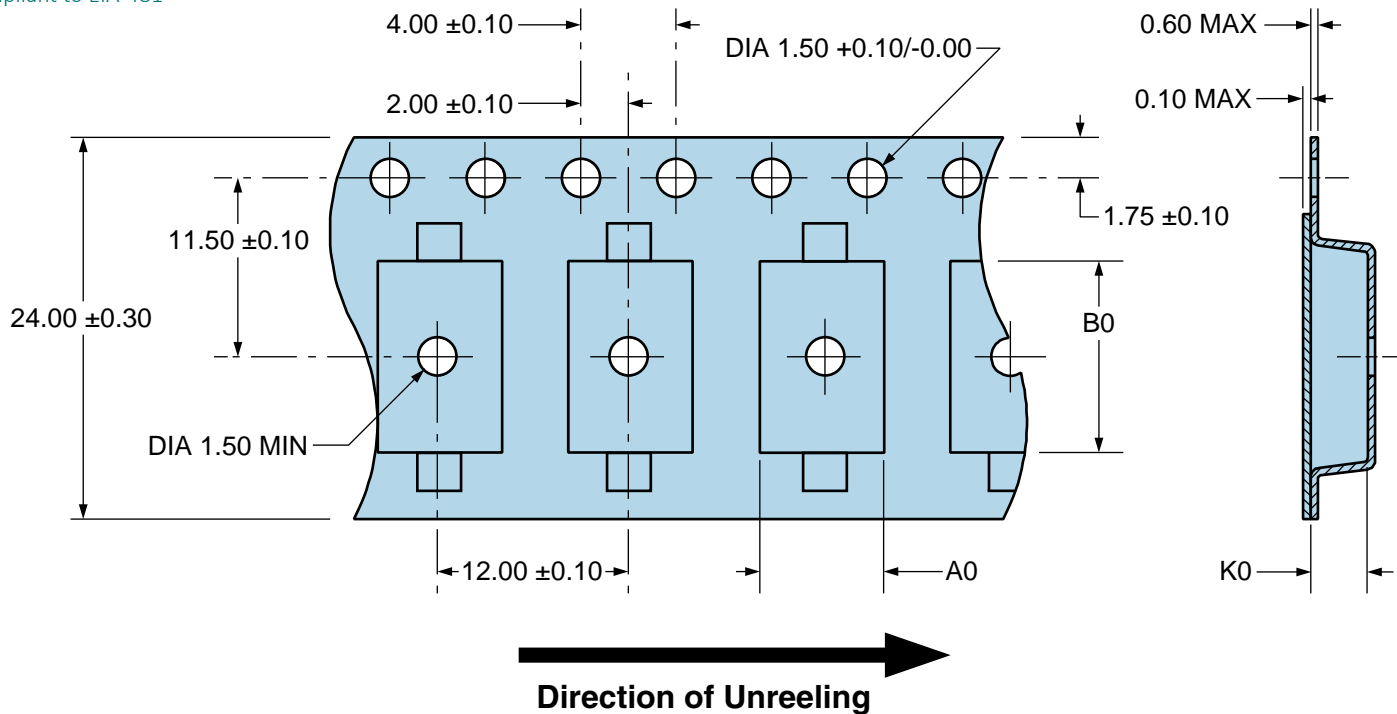
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## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

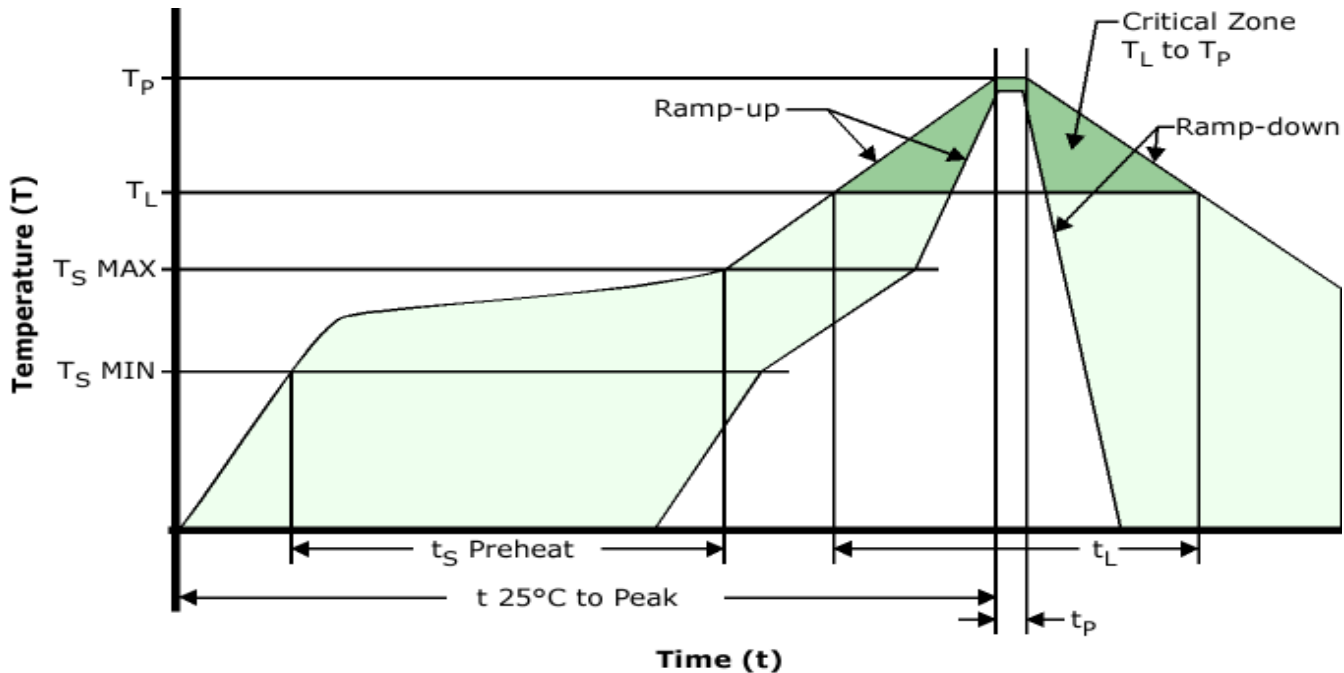
All Dimensions in Millimeters

Compliant to EIA-481



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## Recommended Solder Reflow Methods



## High Temperature Infrared/Convection

$T_S$  MAX to  $T_L$  (Ramp-up Rate) 3°C/Second Maximum

### Preheat

- Temperature Minimum ( $T_S$  MIN) 150°C
- Temperature Typical ( $T_S$  TYP) 175°C
- Temperature Maximum ( $T_S$  MAX) 200°C
- Time ( $t_s$  MIN) 60 - 180 Seconds

Ramp-up Rate ( $T_L$  to  $T_P$ ) 3°C/Second Maximum

### Time Maintained Above:

- Temperature ( $T_L$ ) 217°C
- Time ( $t_L$ ) 60 - 150 Seconds

Peak Temperature ( $T_P$ ) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature ( $T_P$  Target) 250°C +0/-5°C

Time within 5°C of actual peak ( $t_p$ ) 20 - 40 Seconds

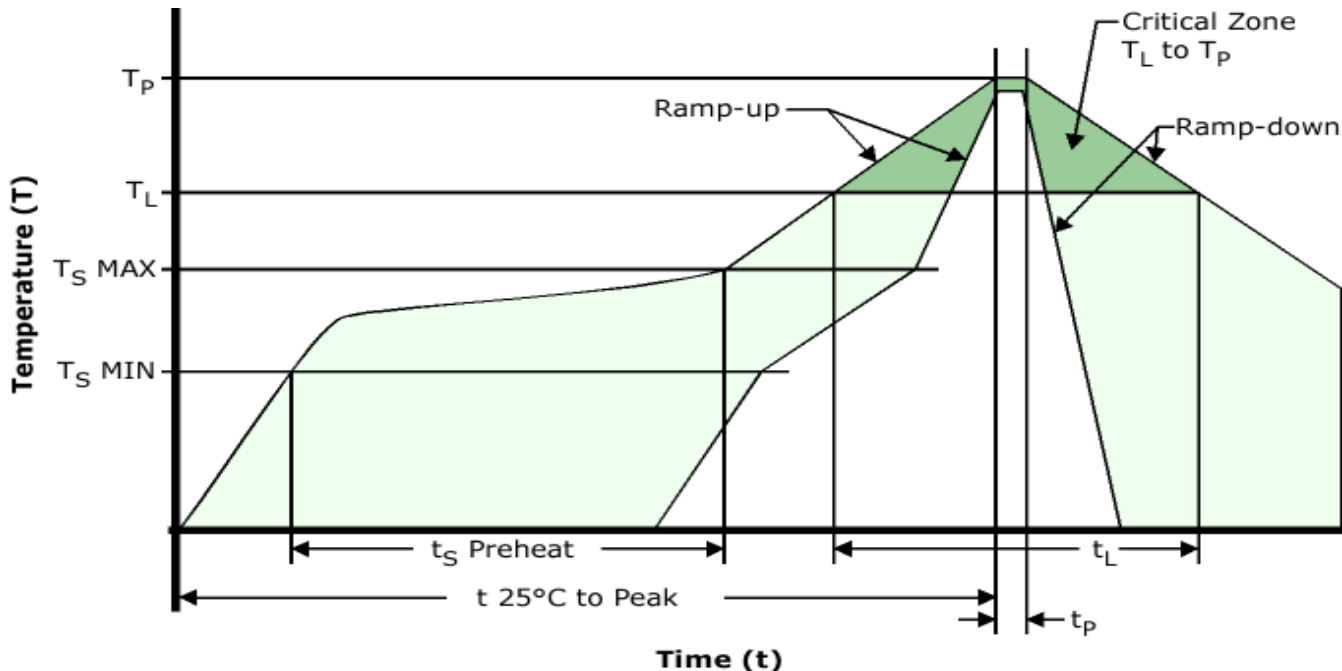
Ramp-down Rate 6°C/Second Maximum

Time 25°C to Peak Temperature (t) 8 Minutes Maximum

Moisture Sensitivity Level Level 1

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 245°C

**T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)** 5°C/Second Maximum

#### Preheat

- Temperature Minimum (T<sub>s</sub> MIN) N/A  
 - Temperature Typical (T<sub>s</sub> TYP) 150°C  
 - Temperature Maximum (T<sub>s</sub> MAX) N/A  
 - Time (t<sub>s</sub> MIN) 30 - 60 Seconds

**Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)** 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C  
 - Time (t<sub>L</sub>) 200 Seconds Maximum

**Peak Temperature (T<sub>P</sub>)** 245°C Maximum

**Target Peak Temperature (T<sub>P</sub> Target)** 245°C Maximum 2 Times / 230°C Maximum 1 Time

**Time within 5°C of actual peak (t<sub>p</sub>)** 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

**Ramp-down Rate** 5°C/Second Maximum

**Time 25°C to Peak Temperature (t)** N/A

**Moisture Sensitivity Level** Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.